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(54) SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF

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(57)**ABSTRACT**

A semiconductor structure including a substrate, multiple first pads, and multiple second pads is provided. The first pads are disposed on the substrate and are separated from each other. The second pads are disposed on the substrate and are separated from each other. Each of the first pads and each of the second pads are separated from each other. A top-view shape of the each of the first pads is different from a top-view shape of the each of the second pads. A portion of the first pads surrounds the same second pad.

